IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

pplicant: Kie Y. Ahn et al.

Examiner:

Douglas M. Menz

Serial No.:

S/N 10/789.044

10/789,044

Group Art Unit: Docket:

2891 1303.070US2

Filed: Title:

February 27, 2004

LANTHANIDE DOPED TIOX DIELECTRIC FILMS

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

MS Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 et. seq., the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Supplemental Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(c)(2), Applicants have included the fee of \$180.00 as set forth in 37 C.F.R. §1.17(p). Please charge any additional fees or credit any overpayment to Deposit Account No. 19-0743.

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The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Pursuant to 37 C.F.R. 1.98(a)(2), Applicant believes that copies of cited U.S. Patents and Published Applications are no longer required to be provided to the Office. Notification of this change was provided in the United States Patent and Trademark Office OG Notices dated October 12, 2004. Thus, Applicant has not included copies of any US Patents or Published Applications cited with this submission. Should the Office require copies to be provided, Applicant respectfully requests that notice of such requirement be directed to Applicant's below-signed representative. Applicant acknowledges the requirement to submit copies of foreign patent documents and non-patent literature in accordance with 37 C.F.R. 1.98(a)(2).

Respectfully submitted,

KIE Y. AHN ET AL.

By their Representatives,

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Date 16 August 2005

Зу ___

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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this ______ day of August, 2005.

Name

Signature X

PTO/SB/08A(10-01)
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Substitute for form 1449A/PTO INFORMATION DISCLOSURE **Application Number** 10/789,044 STATEMENT BY APPLICANT (Use as many sheets as necessa **Filing Date** February 27, 2004 **First Named Inventor** Ahn, Kie 2891 **Group Art Unit** Menz, Douglas **Examiner Name** Attorney Docket No: 1303.070US2 Sheet 1 of 2

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DATE CONSIDERED

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EXAMINER